

Abstract.

A solid state silicon-based condenser microphone comprising a silicon transducer chip (1). The transducer chip includes a backplate (13) and a diaphragm (12) arranged substantially parallel to each other with a small air gap in between, thereby forming an electrical capacitor. The diaphragm (12) is movable relative to the backplate (13) in response to incident sound. An integrated electronic circuit chip (3) or ASIC is electrically coupled to the transducer chip (1). An intermediate layer (2) fixes the transducer chip (1) to the integrated electronic circuit chip (3) with the transducer chip (1) on a first side of the intermediate layer (2) and the integrated electronic circuit chip (3) on a second side of the intermediate layer (2) opposite the first side. The intermediate layer (2) has a sound inlet (4) on the same side as the ASIC giving access of sound to the diaphragm.

09182266-103098